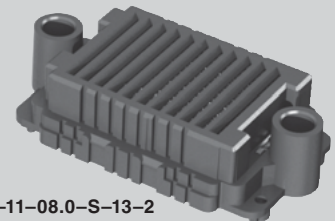


HDAM-11-12.0-S-13-2



HDAF-11-08.0-S-13-2

(2,00 mm) .0787"

HDAM, HDAF SERIES

# RUGGED ELEVATED HIGH DENSITY ARRAY

HDAM Mates with:  
HDAF  
HDAF Mates with:  
HDAM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HDAM](http://www.samtec.com?HDAM) or [www.samtec.com?HDAF](http://www.samtec.com?HDAF)

### Insulator Material:

Black LCP

### Contact Material:

Copper Alloy

### Plating:

Au or Sn over  
50µ" (1,27 µm) Ni

### Current Rating:

3.4 A per pin  
(6 adjacent pins powered)

### Operating Temp Range:

-55°C to +125°C

### Contact Resistance:

19 mΩ

### Working Voltage:

200 VAC

### Mated Cycles:

100

### RoHS Compliant:

Yes

### Lead-Free Solderable:

Yes

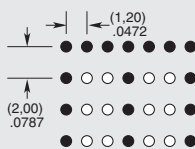
## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## DIFFERENTIAL APPLICATIONS



| ARRAY | PAIR COUNT* |
|-------|-------------|
| 11x13 | 44          |
| 15x13 | 60          |
| 23x13 | 92          |

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

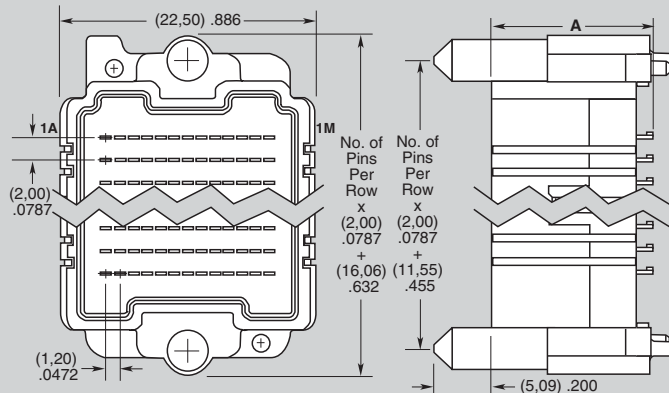
- Tin-Lead Solder Charge
  - Other platings
- Contact Samtec.

**Note:** HD Mezz is a trademark of Molex Incorporated

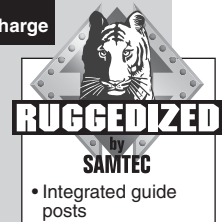
**Note:** Some lengths, styles and options are non-standard, non-returnable.

| HDAM | NO. OF PINS PER ROW | LEAD STYLE                    | PLATING OPTION                                                                       | NO. OF ROWS | SOLDER TYPE                                                                  | OTHER OPTION             |
|------|---------------------|-------------------------------|--------------------------------------------------------------------------------------|-------------|------------------------------------------------------------------------------|--------------------------|
|      | -11, -15, -23       | Specify LEAD STYLE from chart | -S<br>= 30µ" (0,76 µm)<br>Gold on contact area,<br>Matte Tin on tails and guide pins | -13         | -2<br>= Lead-Free Tin Alloy<br>95.5% Sn/<br>3.8% Ag/0.7% Cu<br>Solder Charge | -P<br>= Pick & Place Pad |

**Final Inch**  
CERTIFIED  
Patent Pending



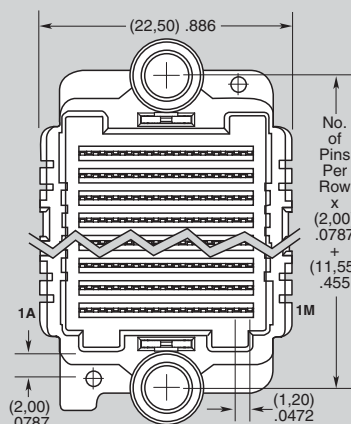
| LEAD STYLE | A            |
|------------|--------------|
| -12.0      | (14,41) .567 |
| -17.0      | (19,41) .764 |



| HDAM/HDAF 35 mm Stack Height | Rated @ 3dB Insertion Loss* |
|------------------------------|-----------------------------|
| Single-Ended Signaling       | 9 GHz / 18 Gbps             |
| Differential Pair Signaling  | 9 GHz / 18 Gbps             |

\*Data based on simulations using Final Inch® design.  
\*Performance data includes effects of a non-optimized PCB.  
Performance data for other stack heights and complete test data available at [www.samtec.com?HDAM](http://www.samtec.com?HDAM), [www.samtec.com?HDAF](http://www.samtec.com?HDAF) or contact [sig@samtec.com](mailto:sig@samtec.com)

| HDAF | NO. OF PINS PER ROW | LEAD STYLE                    | PLATING OPTION                                                                      | NO. OF ROWS | SOLDER TYPE                                                                      | OTHER OPTION             |
|------|---------------------|-------------------------------|-------------------------------------------------------------------------------------|-------------|----------------------------------------------------------------------------------|--------------------------|
|      | -11, -15, -23       | Specify LEAD STYLE from chart | -S<br>= 30µ" (0,76 µm)<br>Gold on contact area,<br>Matte Tin on tails and weld tabs | -13         | -2<br>= Lead-Free Tin Alloy<br>95.5% Sn/<br>3.8% Ag/<br>0.7% Cu<br>Solder Charge | -P<br>= Pick & Place Pad |



| LEAD STYLE | A            |
|------------|--------------|
| -08.0      | (10,51) .414 |
| -18.0      | (20,51) .807 |

